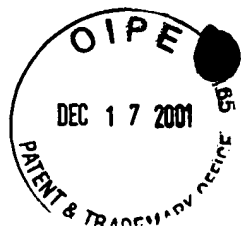


PATENT



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DOCKET NO. 45475-00026
99-44650

DEC 26 2001
IC 2800 MAIL ROOM

VERSION OF AMENDED SECTION OF SPECIFICATION
WITH MARKINGS TO REFLECT CHANGES MADE

The text to be deleted from the table as filed has been struck through. The text to be added to the table as filed is preceded and followed by the traditional double hyphens.

Attorney- Docket No. --Application Number--	Title of Application	First Named Inventor
45475-00013 --09/687,787--	Improved Thin and Heat Radiant Semiconductor Package and Method for Manufacturing	Jae Hun Ku
45475-00014 --09/687,331--	Leadframe for Semiconductor Package and Mold for Molding the Same	Young Suk Chung
45475-00017 --09/687,532--	Method for Making a Semiconductor Package Having Improved Defect Testing and Increased Production Yield	Tae Heon Lee
45475-00018 --09/687,876--	Near Chip Size Semiconductor Package	Sean Timothy Crowley
45475-00022 --09/687,536--	End Grid Array Semiconductor Package	Jae Hun Ku
45475-00027 --09/687,585--	Semiconductor Package Having Reduced Thickness	Tae Heon Lee
45475-00029 --09/687,541--	Semiconductor Package Leadframe Assembly and Method of Manufacture	Young Suk Chung
45475-00030 --09/687,049--	Improved Method for Making Semiconductor Packages	Young Suk Chung

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REMARKS

Applicants request the Examiner to amend the application as requested above. The amendments made are limited to replacing the column titled "Attorney Docket No." which identified U.S. patent applications by docket number with a column titled "Application Number" which identifies the same pending U.S. patent applications by serial number. At the time of filing the present application, the serial numbers of the applications identified in the table above were not available. Applicants have replaced each docket number of the table with the serial number of the application to which it corresponds.

Applicants request that the Examiner amend the specification as discussed and indicated herein. The amendment is to include serial numbers of patent applications which were filed on the same day as the present application, and were therefore unavailable at the time of filing this application. No new matter has been added.

No supplemental fees are believed to be required for entry of this Preliminary Amendment. However, the Commissioner is hereby authorized to charge any amount required in connection therewith to deposit account number 10-0447 of Jenkins & Gilchrist, P.C.

Respectfully submitted,

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5 Referring now to Figure 7, an alternative semiconductor package 800 featuring
internal leads 730a - 730e which are of at least two different lengths L1 and L2. As
shown here, the internal leads proximate to any one side of the chip paddle, for example
730a - 730e, may again be divided into at least two subgroups referred to as outer leads
730d and 730e which are closest to the corners and inner leads 730a, 730b and 730c
10 which are between the outer leads 730d and 730e and centrally located along the side
710a of the chip paddle 710. In this alternative embodiment, the outer leads have a first
length L1 and are longer than the inner leads which have a length L2 or less (e.g. 730b).
By way of example only, L1 may be as long as 0.90 mm and L2 may be as short as 0.25
mm. This is true of the internal leads 730 proximate the other three sides of the chip
15 paddle 710 as well. As noted earlier in discussing leadframe design, this structure is
preferably applied in large size MLF packages to address solder joint strength problems
which may appear in the corner regions of the package body. As noted earlier, the
embodiment set forth in Figure 7 is best suited to large size applications as there is a
reduced tendency for short circuiting in the corners in comparison with small size
20 applications. Note also that MLF packages of 10x10 mm size could be considered
relatively large, but that leadframes and packages could also be produced in accordance
with the present invention in other industry standard sizes (e.g. 20x20, 24x24, 28x28,
32x32 and 40x40 mm).

25 The following applications are all being filed on the same date as the present
application and all are incorporated by reference as if wholly rewritten entirely herein,
including any additional matter incorporated by reference therein:

Application Number	Title of Application	First Named Inventor
09/687,787	Thin and Heat Radiant Semiconductor Package and Method for Manufacturing	Jae Hun Ku
09/687,331	Leadframe for Semiconductor Package and Mold for Molding the Same	Young Suk Chung
09/687,532	Method for Making a Semiconductor Package Having Improved Defect Testing and Increased Production Yield	Tae Heon Lee
09/687,876	Near Chip Size Semiconductor Package	Sean Timothy Crowley

09/687,536	End Grid Array Semiconductor Package	Jae Hun Ku
09/687,585	Semiconductor Package Having Reduced Thickness	Tae Heon Lee
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09/687,049	Method for Making Semiconductor Packages	Young Suk Chung

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It is thus believed that the operation and construction of the present invention will be apparent from the foregoing description of the preferred embodiments. While the leadframe and semiconductor package shown are described as being preferred, it will be obvious to a person of ordinary skill in the art that various changes and modifications may be made therein without departing from the spirit and the scope of the invention, as defined in the following claims. Therefore, the spirit and scope of the appended claims should not be limited to the description of the preferred embodiments contained herein.